

L Number	Hits	Search Text	DB	Time stamp
19	343	(702/94).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:21
20	16	((702/94).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:21
21	189	(702/95).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:22
22	4	((702/95).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 16:00
25	709	(702/150).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:32
26	18	((702/150).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:32
27	251	(702/151).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:53
28	6	((702/151).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
47	210	(702/152).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
48	3	((702/152).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:54
49	173	(702/153).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:55
54	14	((undetected\$4 or (un adj detect\$5)) with (align\$6 near mark\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:19
55	34	((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3)) and (mark\$1 with (substrate\$1 or semiconductor or (semi adj conductor\$1) or wafer\$1)) and pattern\$1 and (mark\$5 with reference\$1) and ((mark\$1 or image\$1) near (portion\$1 or part\$1 or partial\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:02

58	0	((("not" adj detect\$5) with (align\$6 near mark\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 11:20
63	661	(356/614,620).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:00
64	53	((356/614,620).CCLS.) and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:00
65	42	((356/614,620).CCLS.) and (align\$7 with mark\$1) and (image\$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:31
66	1852	(382/141,144,151).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:31
67	129	((382/141,144,151).CCLS.) and (align\$7 with mark\$1) and (image\$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:31
68	80	((382/141,144,151).CCLS.) and (align\$7 near mark\$1) and (image\$1 or imaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 16:32
-	4	"6571196"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:11
-	38	KOSUGE-SHOGO	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:15
-	1001	(hitachi).asn. and (align\$7 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/06 10:16
-	744	(hitachi).asn. and (align\$7 near mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:17
-	312	(hitachi).asn. and (align\$7 near mark\$1) and ((detect\$6 or determin\$7) with position\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:17
-	49	(hitachi).asn. and (align\$7 near mark\$1) and ((detect\$6 or determin\$7) with position\$1) and register\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:18
-	3	(hitachi).asn. and (align\$7 near mark\$1) and ((detect\$6 or determin\$7) with position\$1) and register\$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/05 09:21

-	2	(hitachi).asn. and (align\$7 near target\$1) and ((detect\$6 or determin\$7) with position\$1) and register\$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:22
-	289	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and register\$4 and video	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:23
-	235	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and register\$4 and video and pattern\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:17
-	24	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and register\$4 and video and pattern\$1 and (line adj width\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 09:25
-	3165	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and (image\$1 or imaging or video) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:23
-	1660	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:24
-	1018	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:32
-	102	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and (register\$6 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:16
-	180	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and (regist\$8 with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 10:39
-	179	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:19

-	117	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with align\$6 near (mark\$1 or target\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:14
-	52	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and (register\$6 with mark\$1) and ((line adj width\$1) or inspect\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:16
-	96	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1) and ((part or parts or partial\$4) with mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:25
-	54	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1) and ((part or parts or partial\$4) near3 mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 11:26
-	74	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1) and ((part or parts or partial\$4) near3 (mark\$1 or image\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 12:55
-	6	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1) and (((part or parts or partial\$4) near3 (mark\$1 or image\$1)) with regist\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:09
-	10	(align\$7 near (target\$1 or mark\$1)) and ((detect\$6 or determin\$7) with position\$1) and ((image\$1 or imaging or video) with mark\$1) and pattern\$1 and (semiconductor\$1 or (semi adj conductor\$1) or wafer\$1 or substrate\$1) and (mark\$1 with reference\$1) and ((register\$4 or registration) with mark\$1) and (((part or parts or partial\$4) with (mark\$1 or image\$1)) with regist\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:19

-	0	((image or imaging) with (alignment near mark\$1 ) with reference\$1) and (regist\$9 with (alignment near mark\$1 ) with (part\$1 or partial\$4)) and ((image or imaging) with (alignment near mark\$1 ) with inspect\$1) and ((detect\$6 or determin\$5) with position\$1 with (alignment near mark\$1 ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:24
-	0	((image or imaging) with mark\$1 with reference\$1) and ((regist\$9 with mark\$1 ) with (part\$1 or partial\$4)) and ((image or imaging) with mark\$1 with inspect\$1) and ((detect\$6 or determin\$5) with position\$1 with mark\$1 ) and (align\$6 near mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:27
-	2	((image or imaging) with mark\$1 with reference\$1) and ((regist\$9 with mark\$1 ) with (part\$1 or partial\$4)) and ((image or imaging) with (mark\$1 and inspect\$1)) and ((detect\$6 or determin\$5) with (position\$1 and mark\$1 ) ) and (align\$6 near mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:30
-	4	((image or imaging) with mark\$1 ) with reference\$1) and ((regist\$9 with (mark\$1 or image\$3 ) with (part\$1 or partial\$4)) and ((image or imaging) with inspect\$6) with mark\$1 ) and ((detect\$6 or determin\$5) with position\$1 ) with mark\$1 ) and (align\$6 near mark\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 13:39
-	36	(line near width\$1) and ((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:14
-	145	((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3)) and (mark\$1 with (substrate\$1 or semiconductor or (semi adj conductor\$1) or wafer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:17
-	93	((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3)) and (mark\$1 with (substrate\$1 or semiconductor or (semi adj conductor\$1) or wafer\$1)) and pattern\$1 and (mark\$5 with reference\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:34
-	79	((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3)) and (mark\$1 with (substrate\$1 or semiconductor or (semi adj conductor\$1) or wafer\$1)) and pattern\$1 and (mark\$5 with reference\$1) and (mark\$1 with (portion\$1 or part\$1 or partial\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/05 15:46
-	89	((alignment\$1 near mark\$1) with regist\$8) and ((alignment\$1 near mark\$1) with (image\$1 or imaging\$3)) and (mark\$1 with (substrate\$1 or semiconductor or (semi adj conductor\$1) or wafer\$1)) and pattern\$1 and (mark\$5 with reference\$1) and ((mark\$1 or image\$1) with (portion\$1 or part\$1 or partial\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:01